

applicants: Chan, et al. Serial No. 09/886,741 -

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Title: MULTI-DIE MODULE AND METHOD THEREOF

Box Non-Fee Amendment Commissioner for Patents U.S. Patent and Trademark Office Washington, D.C. 20231

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Patricia O'Donoghue

AMENDMENT UNDER 37 C.F.R. §1.111

Dear Sir:

This Amendment is being submitted in response to the Office Action dated August 14, 2002, relating to the above-identified application. Reexamination and reconsideration of said application are respectfully requested.

IN THE SPECIFICATION

Please amend the specification as provided below. Pursuant to 37 C.F.R. §1.121, a marked-up version of the following paragraph(s) is provided at the end of this Amendment as Exhibit A.

Please replace the paragraph beginning on page 3, line 22, with the following:

In the embodiment illustrated, package module 100 has unpackaged die 110 mounted on it, as well as packaged die 120 and 130. In at least one embodiment, unpackaged die 110 is a data processor, such as a general purpose processor or a graphics processor, and packaged die 120 and 130 are memory packaged in Chip Scale Packages (CSP) or stacked CSP memories. In other embodiments, unpackaged die 110 may be an additional processor such as an audio processor, a general purpose processor, a controller, etc., while packaged die 120 and 130 may be static random access memories (SRAM), dynamic random access memories (DRAM), read only memories (ROM), flash memories, electrically erasable programmable memories (EEPROMS), or any other suitable memory type or combination of types. In addition, packaged